

ABSTRACT

**COMPOUND, CURABLE RESIN COMPOSITION AND CURED PRODUCT
THEREFROM, AND METHOD FOR PRODUCING COMPOUND**

Provided are a compound that exhibits an excellent solvent stability and excellent low dielectric characteristics, and a curable resin composition and a cured product therefrom. This compound is the compound given by formula (1), wherein the compound for which n in formula (1) is 1 is less than 50%, as the GPC area percentage, in the total compound. (In formula (1), the multiple R's each independently represent a C1-C10 hydrocarbon group or halogenated alkyl group. p and r are integers from 0-4, and q is an integer from 0-3. n is the number of repetitions, and the average value n_{ave} of n satisfies $1 \leq n_{ave} \leq 20$.)

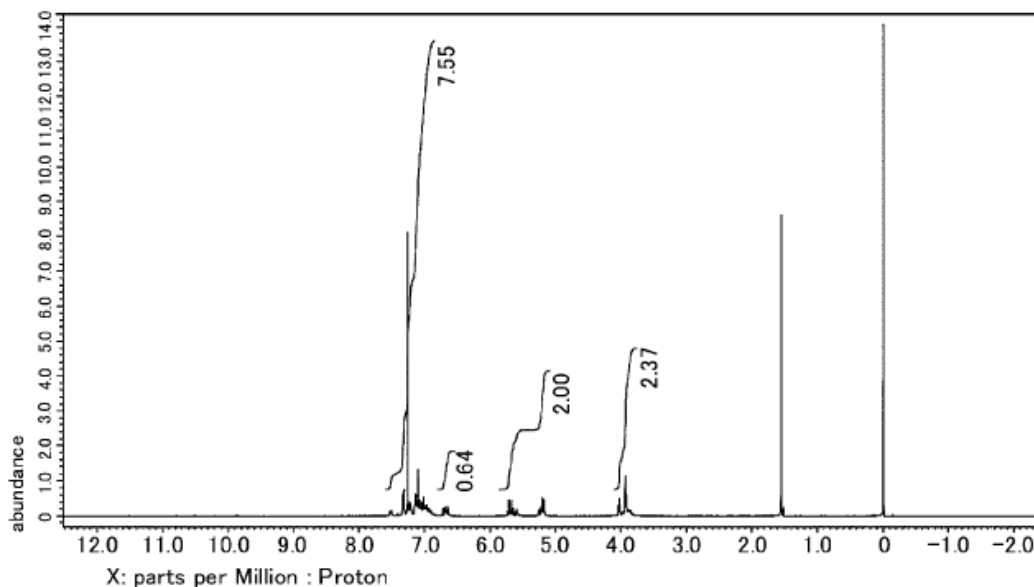
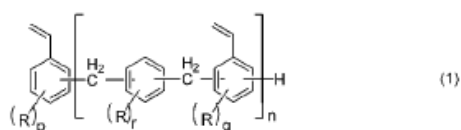


Figure 3